



100V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

BV _{DSS}	Rds(on)	I _D Tc = +25°C
100V	$28m\Omega$ @ V _{GS} = 10V	40A

Description and Applications

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- Power-management functions
- DC-DC converters

Features and Benefits

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- <1.1mm Package Profile Ideal for Thin Applications
- Lead-Free Finish; RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

https://www.diodes.com/quality/product-definitions/

An automotive-compliant part is available under separate datasheet (DMNH10H028SPSQ)

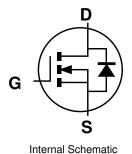
Mechanical Data

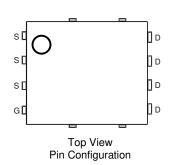
- Package: PowerDI®5060-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Terminals: Finish Matte Tin Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.097 grams (Approximate)





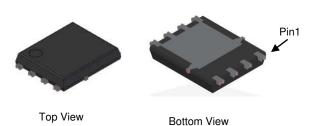
Bottom View

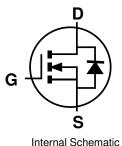


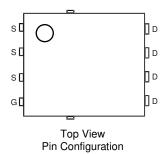


Site 2:

PowerDI5060-8 (SWP) (Type UX)







Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.



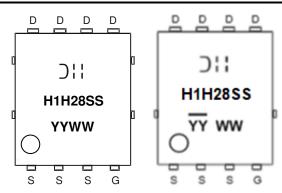
Ordering Information (Note 4)

Part Number	Pookogo	Packing		
Part Number Package		Qty.	Carrier	
DMNH10H028SPS-13	PowerDI5060-8	2,500	Tape & Reel	
DMNH10H028SPS-13	PowerDI5060-8 (SWP) (Type UX)	2,500	Tape & Reel	

Note:

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



⊃!!=Manufacturer's Marking H1H28SS = Product Type Marking Code YYWW = Date Code Marking YY or \overline{YY} = Year (ex: 23 = 2023) WW = Week Code (01 to 53)

Maximum Ratings (@ $T_C = +25^{\circ}C$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	100	V
Gate-Source Voltage			Vgss	±20	V
Continuous Drain Current, V _{GS} = 10V	I _D	40 25	А		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) (Note 5)			I _{DM}	54	Α
Maximum Continuous Body Diode Forward Current (Note 6)			Is	3.9	Α
Avalanche Current (Note 8) L=0.1mH			las	26	Α
Avalanche Energy (Note 8) L=0.1mH			Eas	35	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	1.6	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	97	°C/W
Total Power Dissipation (Note 6)		P _D	2.9	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	RθJA	52	°C/W
Thermal Resistance, Junction to Case		R _θ JC	1.8	°C/ VV
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +175	°C

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. Short duration pulse test used to minimize self-heating effect.

 8. Guaranteed by design. Not subject to product testing.

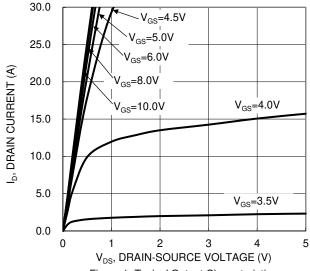


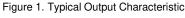
Electrical Characteristics (@T_C = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	100			٧	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS			1.0	μΑ	V _{DS} = 100V, V _{GS} = 0V	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	2.0	2.5	4.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}		19	28	mΩ	$V_{GS} = 10V, I_D = 20A$	
Diode Forward Voltage	V_{SD}	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1.0A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	2245	_	pF	V _{DS} = 50V, V _{GS} = 0V f = 1.0MHz	
Output Capacitance	Coss	_	173	_			
Reverse Transfer Capacitance	Crss	_	68	_			
Gate Resistance	Rg	_	1.9	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1.0MHz$	
Total Gate Charge (V _{GS} = 10V)	Qg	_	36	_		V _{DD} = 50V, I _D = 20A	
Total Gate Charge (V _{GS} = 6.0V)	Qg	_	22	_	nC		
Gate-Source Charge	Qgs	_	7.3	_	IIC		
Gate-Drain Charge	Qgd	_	9.2	_			
Turn-On Delay Time	td(ON)	_	6.4	_		$V_{GS} = 10V, V_{DS} = 50V,$ $R_{G} = 3.0\Omega, I_{D} = 20A$	
Turn-On Rise Time	t _R	_	5.8	_	ns		
Turn-Off Delay Time	tD(OFF)	_	17.8	_			
Turn-Off Fall Time	tr	_	4.8	_			
Reverse Recovery Time	trr	_	35	_	ns	IF = 20A, di/dt = 100A/μs	
Reverse Recovery Charge	Qrr	_	47		nC	$I_F = 20A$, $di/dt = 100A/\mu s$	

7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing. Notes:







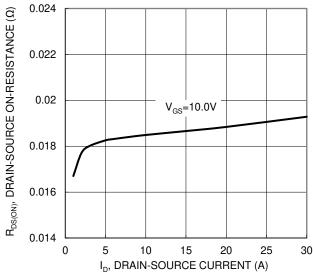


Figure 3. Typical On-resistance vs. Drain Current and Gate Voltage

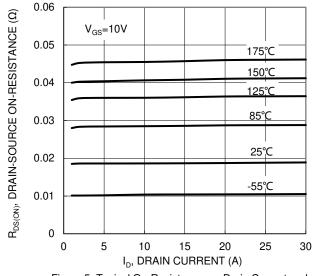


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

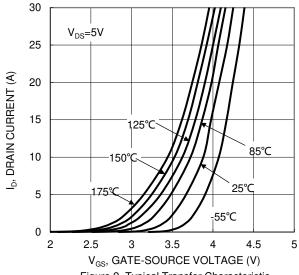


Figure 2. Typical Transfer Characteristic

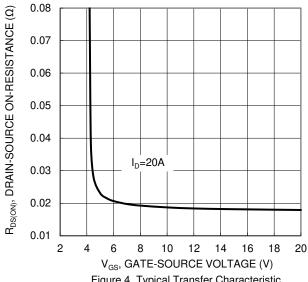


Figure 4. Typical Transfer Characteristic

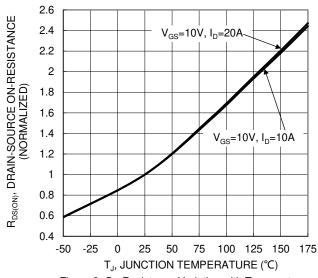


Figure 6. On-Resistance Variation with Temperature



DMNH10H028SPS

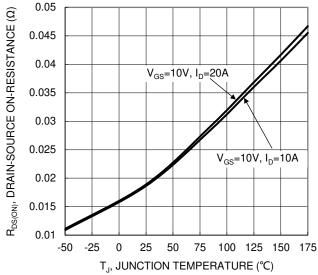
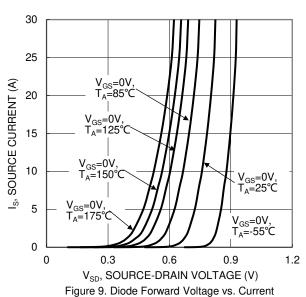
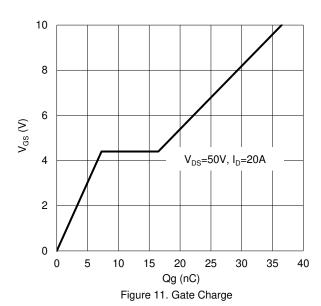


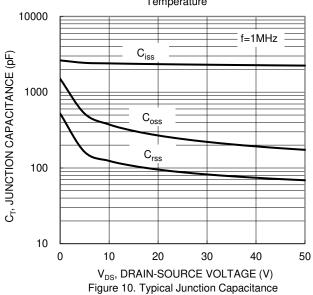
Figure 7. On-Resistance Variation with Temperature





3.2 $V_{\text{GS(TH)}},$ GATE THRESHOLD VOLTAGE (V) 3 2.8 2.6 2.4 $I_D=1mA$ 2.2 2 $I_{D} = 250 \mu A$ 1.8 1.6 1.4 1.2 -25 -50 0 25 50 75 100 125 150 T_J, JUNCTION TEMPERATURE (°C)

Figure 8. Gate Threshold Variation vs. Junction Temperature



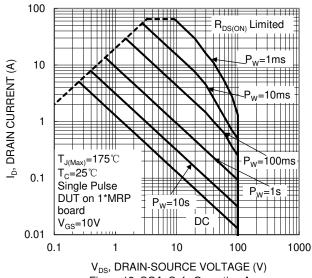


Figure 12. SOA, Safe Operation Area



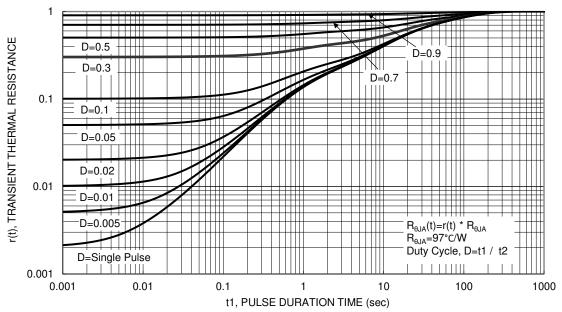


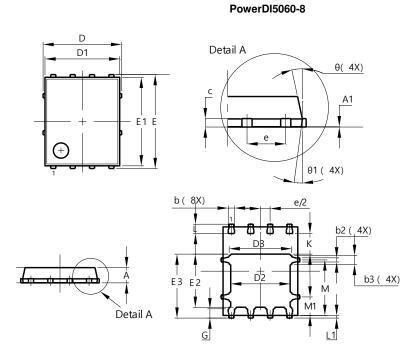
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

Site 1:



PowerDI5060-8					
Dim	Min	Max	Тур		
Α	0.90	1.10	1.00		
A 1	0.00	0.05	-		
b	0.33	0.51	0.41		
b2	0.200	0.350	0.273		
b3	0.40	0.80	0.60		
С	0.230	0.330	0.277		
D	ļ	5.15 BSC			
D1	4.70	5.10	4.90		
D2	3.70	4.10	3.90		
D3	3.90	4.30	4.10		
Е	6.15 BSC				
E1	5.60	6.00	5.80		
E2	3.28	3.68	3.48		
E3	3.99	4.39	4.19		
е	1.27 BSC				
G	0.51	0.71	0.61		
K	0.51	-	-		
L	0.51	0.71	0.61		
L1	0.100	0.200	0.175		
М	3.235	4.035	3.635		
М1	1.00	1.40	1.21		
Θ	10°	12°	11°		
Θ1	6°	8°	7°		
All Dimensions in mm					

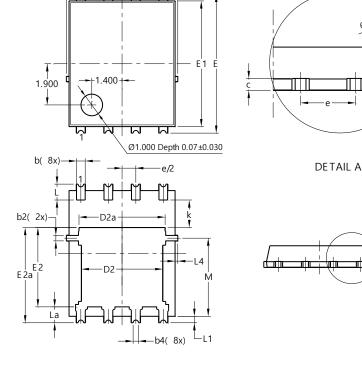
Site 2:

PowerDI5060-8/SWP (Type UX)

Seating Plane

(a)(kg)

DETAIL A



(Type UX)				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A1	0	0.05		
b	0.30	0.50	0.41	
b2	0.20	0.35	0.25	
b4	C).25REF		
C	0.230	0.330	0.277	
D	5	.15 BS0	\circ	
D1	4.70	5.10	4.90	
D2	3.56	3.96	3.76	
D2a	3.78	4.18	3.98	
Е	6	6.40 BSC		
E1	5.60	6.00	5.80	
E2	3.46	3.86	3.66	
E2a	4.195	4.595	4.395	
е	1.27BSC			
k	1.05			
L	0.635	0.835	0.735	
La	0.635	0.835	0.735	
L1	0.200	0.400	0.300	
L1a	0.050REF			
L4	0.025	0.225	0.125	
М	3.205	4.005	3.605	
θ	10°	12°	11°	
θ1	6°	8°	7°	
All Dimensions in mm				

PowerDI5060-8/SWP

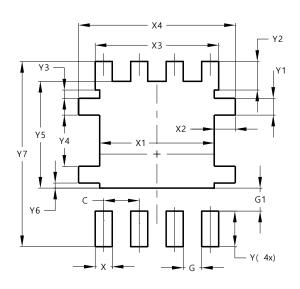


Suggested Pad Layout

 $Please \ see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

Site 1:

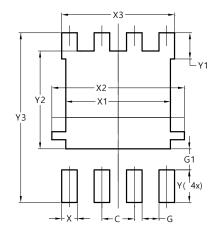
PowerDI5060-8



Dimensions	Value (in mm)
С	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	0.755
Х3	4.420
X4	5.610
Υ	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y7	6.610

Site 2:

PowerDI5060-8/SWP (Type UX)



Dimensions	Value		
	(in mm)		
С	1.270		
G	0.660		
G1	0.820		
X	0.610		
X1	4.100		
X2	5.190		
Х3	4.420		
Υ	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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